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KAMITSUBO et al.(10) **Pub. No.: US 2022/0377886 A1**(43) **Pub. Date: Nov. 24, 2022**(54) **LAMINATED BODY AND METHOD FOR
MANUFACTURING THE SAME****Publication Classification**(71) Applicant: **Murata Manufacturing Co., Ltd.**,
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ABSTRACT

A stacked body includes a first resin layer including a thermoplastic first resin as a main material, a pattern including a conductor layer on one principal surface of the first resin layer, and a second resin layer including a thermoplastic second resin as a main material. The first resin layer is softer than the second resin layer. The first resin layer has a lower dielectric constant than the second resin layer. A pattern including the conductor layer is at least partially embedded in the first resin layer, and includes a portion in contact with the first resin layer along a layer direction (X-Y plane) of the first resin layer and a portion in contact with the first resin layer along a stacking direction (X-Z plane) of the first resin layer, the second resin layer, and the pattern including the conductor layer.

